

L Number	Hits	Search Text	DB	Time stamp
1	5	underbump adj metal adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:45
2	1	underbump adj barrier adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:49
3	61861	barrier adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:49
4	1080	metal adj barrier adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:49
5	83324	bump\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:50
6	60	(metal adj barrier adj layer) and bump\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:10
7	165035	support adj member	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:11
8	17775	second adj area	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:11
9	410	(support adj member) and (second adj area)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:11
10	1705364	substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:11
11	80	((support adj member) and (second adj area)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:12
12	10	((support adj member) and (second adj area)) and substrate) and bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:12

**EAST - [thinhsearch15.wsp:1]**

File View Edit Tools Window Help

L1: (2) "6683369"  
 L2: (4) "2003017654"  
 L3: (2) "20030017654"  
 L4: (17775) second adj area  
 L5: (30381) second adj region  
 L6: (1705364) substrate  
 L7: (4119) resin adj support  
 L8: (7) 5 and 6 and 7  
 L9: (5003) support adj pad  
 L10: (13405) BGA  
 L11: (165035) support adj member  
 L12: (560) 5 and 11  
 L13: (56) 12 and package  
 L14: (1362019) semiconductor  
 L15: (20) 13 and 14  
 L16: (0) resin adj dummy adj bump  
 L17: (167) dummy adj bump  
 L18: (113) 14 and 17  
 L19: (47488) 4 5  
 L20: (2) 18 and 19  
 L21: (37) 17 and resin  
 L22: (122) resin adj bump  
 L23: (89) 14 and 22  
 L24: (2) 23 and dummy  
 L25: (0) plastic adj dummy adj bump  
 L26: (2) 17 near resin  
 L27: (114) resin adj support adj member  
 L28: (16) 14 and 27  
 L29: (60) epoxy adj spacer  
 L30: (2) epoxy adj dummy

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DB: USPAT; USPO; EP0; IPO; DERWENT; IBM; TOB  
Default operator: OR

6175157

Print  Highlight all terms initially

U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Cls	Inventor	S	C	P	2	3	Image	I
1	<input type="checkbox"/>	US 6590286 B2	20030708	12	Land grid array semiconductor device	257/737	257/738; 257/780; 257/666; 257/675; 257/E21.503; 257/E21.514;		Okada, Makio et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6590	
2	<input type="checkbox"/>	US 6583512 B2	20030624	27	Semiconductor device and method for fabricating the same	257/777	257/690; 257/734; 257/786; 257/E23.021; 257/666; 257/683; 257/E21.503;		Nakaoka, Yukiko et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6583	
3	<input type="checkbox"/>	US 6537855 B2	20030325	7	Semiconductor device and method of manufacturing the same	438/118			Taguchi, Yutaka et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6537	
4	<input checked="" type="checkbox"/>	US 6483190 B1	20021119	22	Semiconductor chip element, semiconductor chip element mounting	257/737			Kainuma, Norio et al.	<input type="checkbox"/>	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6483	
5	<input checked="" type="checkbox"/>	US 6462420 B2	20021008	9	Semiconductor chip and semiconductor device having a chip	257/777			Hikita, Junichi et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6462	
6	<input checked="" type="checkbox"/>	US 6426559 B1	20020730	7	Miniature 3D multi-chip module	257/777	257/666; 257/683; 257/E21.503;		Bryan, Robert Newell et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6426	
7	<input type="checkbox"/>	US 6424033 B1	20020723	12	Chip package with grease heat sink	257/718	257/786; 257/E23.021; 257/666; 257/683; 257/E21.503;		Akram, Salman	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6424	

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↗ L29: (60) epoxy adj spacer  
 ↗ L30: (2) epoxy adj dummy  
 ↗ L31: (8) 29 and 14  
 ↗ L32: (122) resin adj bump  
 ↗ L33: (12) plastic adj bump  
 ↗ L34: (37) epoxy adj bump  
 ↗ L35: (30) 14 and 34  
 ↗ L36: (18) dummy adj plastic  
 ↗ L37: (631) resin adj spacer  
 ↗ L38: (68) 14 and 37  
 ↗ L39: (11) 38 and package  
 ↗ L40: (1) 10 and 37  
 ↗ L41: (6) "6208022"  
 ↗ L42: (1474) flexible adj substrate  
 ↗ L43: (7) 17 and 42  
 ↗ L44: (68) support adj bump  
 ↗ L45: (39) 44 and semiconductor  
 ↗ L46: (60308) supporting adj member  
 ↗ L47: (172) 46 and 42  
 ↗ L48: (478) supporting adj spacer  
 ↗ L49: (1) 48 and 42  
 ↗ L50: (0) 48 and semiconductor and package  
 ↗ L51: (25) 48 and semiconductor  
 ↗ L52: (9) "5635756"  
 ↗ L53: (11) "6175157"

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DB: USPAT; US-PPUB; EPO; JPO; DERVENT; IBM\_108  
Default operator: OR  
"6175157"

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BBB term ISR term Images Text HTML

U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Cls	Inventor	S	C	P	Image	Image 1
1	<input type="checkbox"/>	US 6590286 B2	20030708	12	Land grid array semiconductor device	257/737	257/738; 257/780;		Okada, Makio et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6590
2	<input type="checkbox"/>	US 6583512 B2	20030624	27	Semiconductor device and method for fabricating the same	257/777	257/666; 257/675;		Nakao, Yukiko et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6583
3	<input type="checkbox"/>	US 6537855 B2	20030325	7	Semiconductor device and method of manufacturing the same	438/118	257/E21.503;		Taguchi, Yutaka et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6537
4	<input checked="" type="checkbox"/>	US 6483190 B1	20021119	22	Semiconductor chip element, semiconductor chip element mounting	257/737	257/690; 257/734;		Kanuma, Norio et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6483
5	<input type="checkbox"/>	US 6462420 B2	20021008	9	Semiconductor chip and semiconductor device having a chip	257/777	257/786; 257/E23.021;		Hikita, Junichi et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6462
6	<input checked="" type="checkbox"/>	US 6426559 B1	20020730	7	Minature 3D multi-chip module	257/777	257/666; 257/683;		Bryan, Robert Newell et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6426
7	<input type="checkbox"/>	US 6424033 B1	20020723	12	Chip package with grease heat sink and method of making	257/718	257/E21.503; 257/E23.087;		Akram, Salman	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6424
8	<input checked="" type="checkbox"/>	US 6376914 B2	20020423	10	Dual-die integrated circuit package	257/777	257/666; 257/685;		Kovats, Julius A. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6376
9	<input checked="" type="checkbox"/>	US 6285084 B1	20010904	14	Semiconductor device	257/777	257/80; 257/81;		Hikita, Junichi et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6285

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<input checked="" type="checkbox"/> Active <input checked="" type="checkbox"/> L1: (5) underbump adj metal adj layer <input checked="" type="checkbox"/> L2: (1) underbump adj barrier adj layer <input checked="" type="checkbox"/> L3: (61861) barrier adj layer <input checked="" type="checkbox"/> L4: (1080) metal adj barrier adj layer <input checked="" type="checkbox"/> L5: (83324) bump\$1 <input checked="" type="checkbox"/> L6: (60) 4 and 5 <input checked="" type="checkbox"/> L7: (165035) support adj member <input checked="" type="checkbox"/> L8: (17775) second adj area <input checked="" type="checkbox"/> L9: (410) 7 and 8 <input checked="" type="checkbox"/> L10: (1705364) substrate <input checked="" type="checkbox"/> L11: (80) 9 and 10 <input checked="" type="checkbox"/> L12: (10) 11 and bump	
<input type="checkbox"/> Browse <input type="checkbox"/> Details <input type="checkbox"/> Clear DB: USPTO:US_PGPUB:EP0:JPO:DERVENTISBM_TOB Default operator: OR 11 and bump	

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U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Cls	Inventor	S	C	P	X	3	Image Doc
1	<input type="checkbox"/>	US 20030017654	20030123	22	Semiconductor chip having a supporting member, tape substrate, s	438/127	257/E21.503; 257/E23.065;		Iwanoto, Naofumi	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 200300
		A1					174/260	174/267;							
2	<input type="checkbox"/>	US 20020117330	20020829	155	Resilient contact structures formed and then attached to a substrate		257/E21.503;		Eldridge, Benjamin Niles et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 200201
		A1						257/E23.069;							
3	<input type="checkbox"/>	US 20020047214	20020425	18	Multi-chip package-type semiconductor device	257/778	257/E23.125;		Morinaga, Yuichi et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 200200
		A1						257/676							
4	<input type="checkbox"/>	US 20010020546	20010913	155	Electrical contact structures formed by configuring a flexible wire to have	174/261	174/24;		Eldridge, Benjamin N. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 200100
		A1						174/255;							
5	<input type="checkbox"/>	US 20010020545	20010913	155	Electrical contact structures formed by configuring a flexible wire to have	174/260	257/618;		Eldridge, Benjamin N. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 200100
		A1						257/E21.503;							
6	<input checked="" type="checkbox"/>	US 6683369 B2	20040127	20	Semiconductor chip having a supporting member, tape substrate, s	257/676	257/692		Iwanoto, Naofumi	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 668336
7	<input type="checkbox"/>	US 6518655 B2	20030211	16	Multi-chip package-type semiconductor device	257/678	257/686; 257/E23.069;		Morinaga, Yuichi et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 651865
8	<input checked="" type="checkbox"/>	US 6110823 A	20000829	130	Method of modifying the thickness of a plating on a member by creating a te	438/660	257/E21.503;		Eldridge, Benjamin N. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 611082
								257/E21.508;							
9	<input type="checkbox"/>	US 4849857 A	19890718	11	Heat dissipating interconnect tape for use in tape automated bonding	361/708	257/668;		Butt, Sheldon H. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 484985
								257/E23.034;							
10	<input type="checkbox"/>	US 4827376 A	19890502	12	Heat dissipating interconnect tape for use in tape automated bonding	361/708	257/623.034; 257/E23.055;		Voss, Scott V.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 482737

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